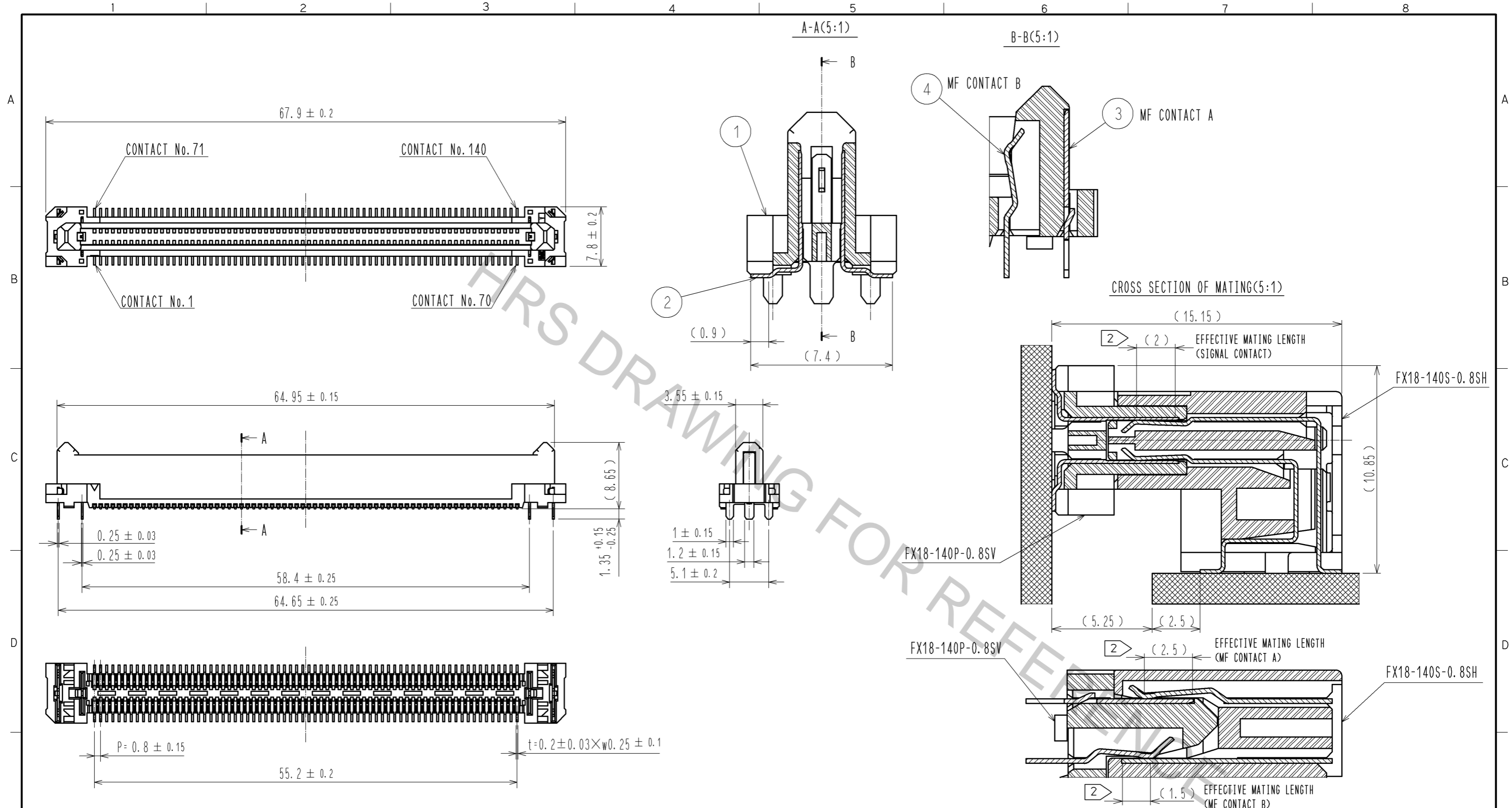


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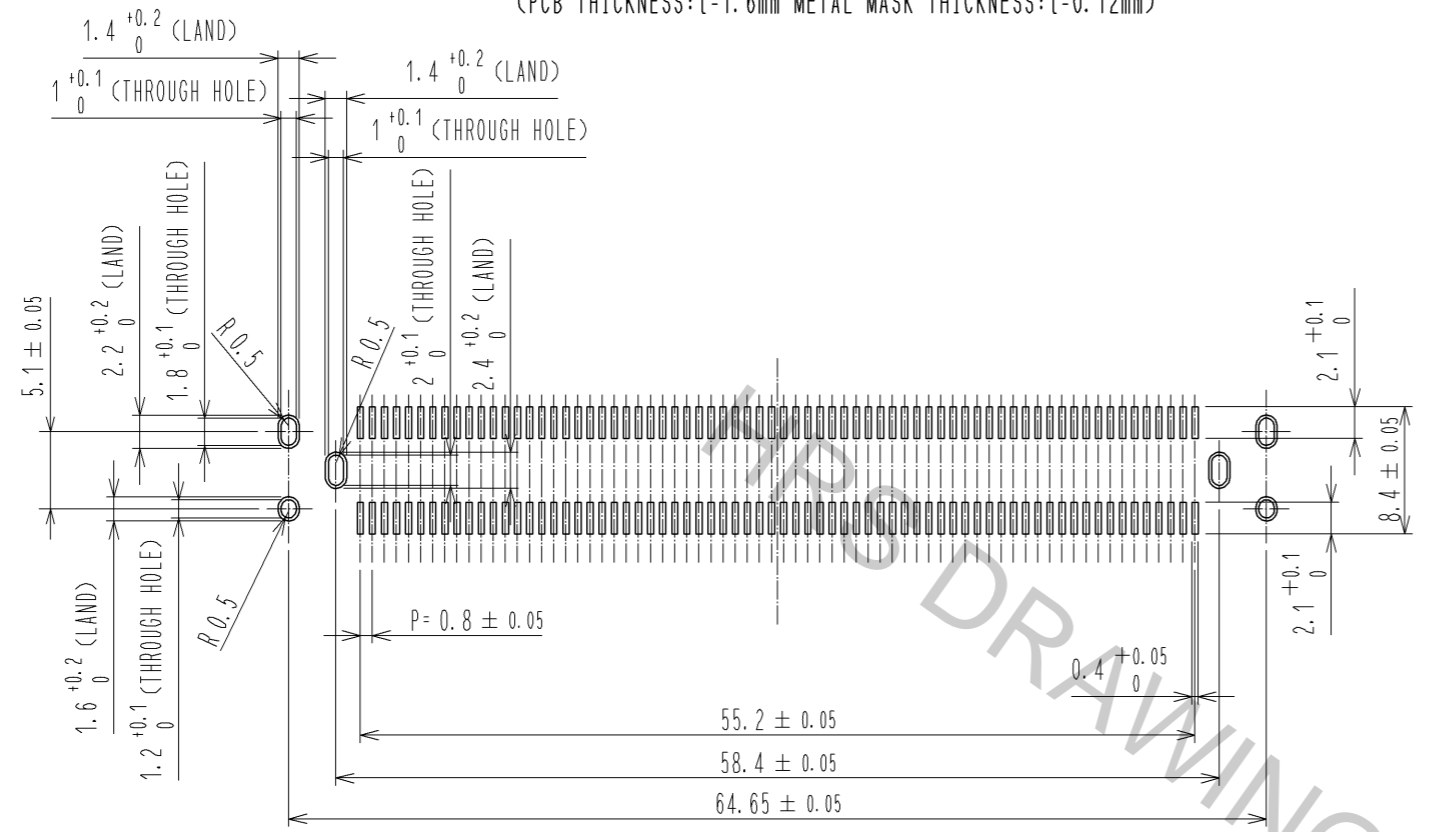
NOTE 1 LEAD CO-PLANARITY IS 0.1mm MAX.
 ② CONTACTS ARE 3 STEPS SEQUENTIAL. (MF CONTACT A->SIGNAL CONTACT->MF CONTACT B)
 WHEN USING THIS SEQUENTIAL STRUCTURE, PLEASE AVOID ANGLED INSERTION.
 3 MF CONTACT A AND MF CONTACT B CAN BE USED AS POWER SUPPLY CONTACT. (3A/PIN MAX)
 ④ IT SHOWS THE VACUUM PICKUP AREA. (SEE PAGE 2)
 REMOVE THE MYLAR TAPE BEFORE MATING CONNECTORS.
 ⑤ THIS IS PACKAGED IN TRAY. (40pcs/TRAY)
 6 BLEMISH AND HIT MARK CAN BE OCCURED THROUGH OUT THE MANUFACTURING PROCESS WHICH DOESN' T AFFECT QUALITY LEVEL.
 7 THE DIMENSIONS IN PARENTHESES ARE FOR REFERENCES.

3	PHOSPHOR BRONZE	CONTACT AREA:GOLD 0.1 μm	6	POLYIMIDE	
		LEAD AREA:TIN-PLATING 1 μm			
2	PHOSPHOR BRONZE	UNDER PLATING:NICKEL 1.3 μm	5	POLYSTYRENE	
		CONTACT AREA:GOLD 0.1 μm			
1	POLYAMIDE	LEAD AREA:GOLD 0.03 μm	4	PHOSPHOR BRONZE	CONTACT AREA:GOLD 0.1 μm
		UNDER PLATING:NICKEL 1.3 μm			LEAD AREA:TIN-PLATING 1 μm
NO.	MATERIAL	FINISH . REMARKS	NO.	MATERIAL	FINISH . REMARKS
1	POLYAMIDE	BLACK UL94V-0	4	PHOSPHOR BRONZE	CONTACT AREA:GOLD 0.1 μm LEAD AREA:TIN-PLATING 1 μm UNDER PLATING:NICKEL 1.3 μm

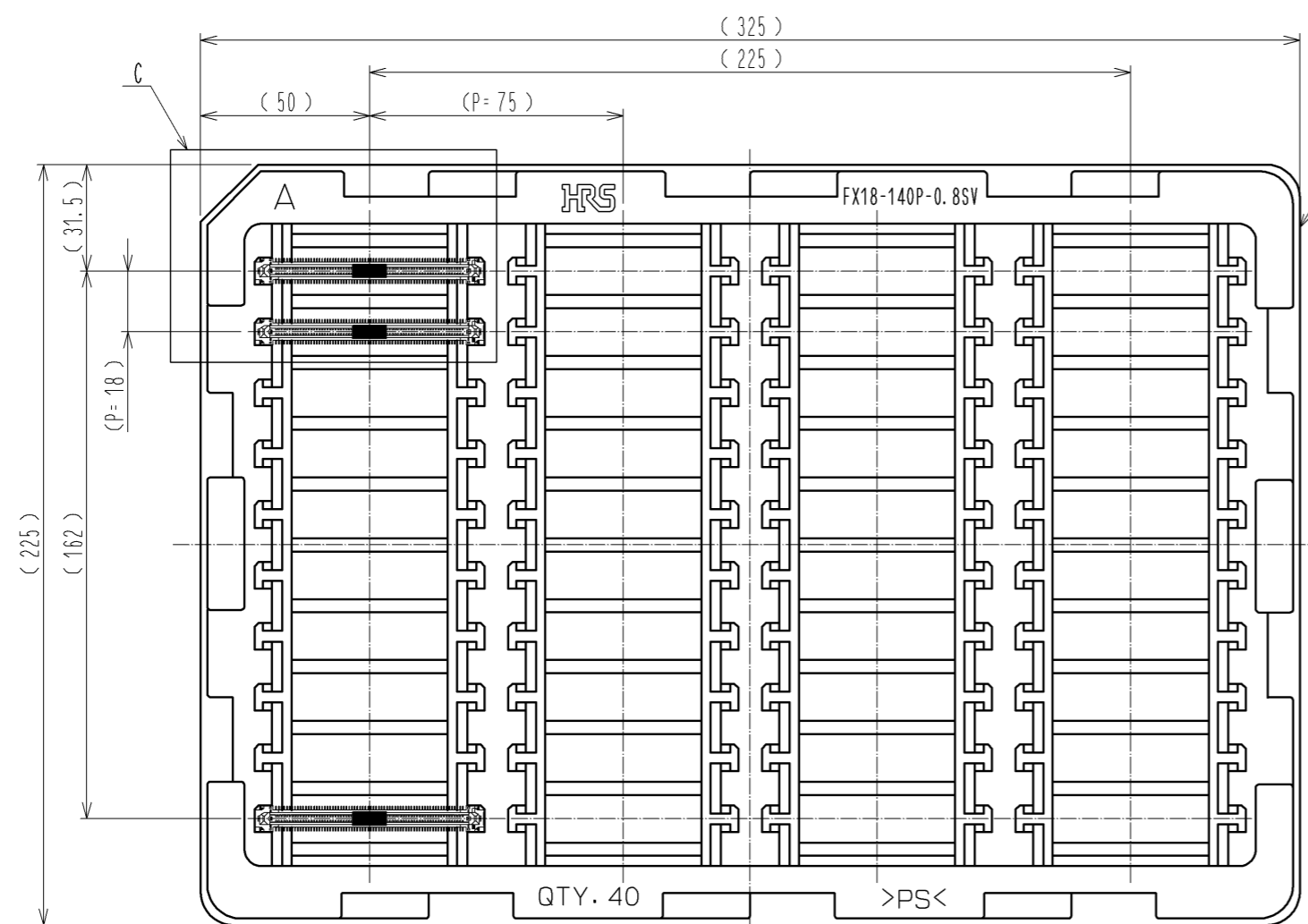
UNITS mm		SCALE 2 : 1	COUNT △	DESCRIPTION OF REVISIONS	DESIGNED	CHECKED	DATE
APPROVED : HS. OKAWA		12.01.25		DRAWING NO.	EDC3-159565-00		
CHECKED : KI. HIROKAWA		12.01.25		PART NO.	FX18-140P-0.8SV		
DESIGNED : TH. SANO		12.01.25		CODE NO.	CL579-0021-0-00		
DRAWN : TH. SANO		12.01.25					

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RECOMMENDED LAND PATTERN DIMENSION OF PCB(2:1)
(PCB THICKNESS:t=1.6mm METAL MASK THICKNESS:t=0.12mm)

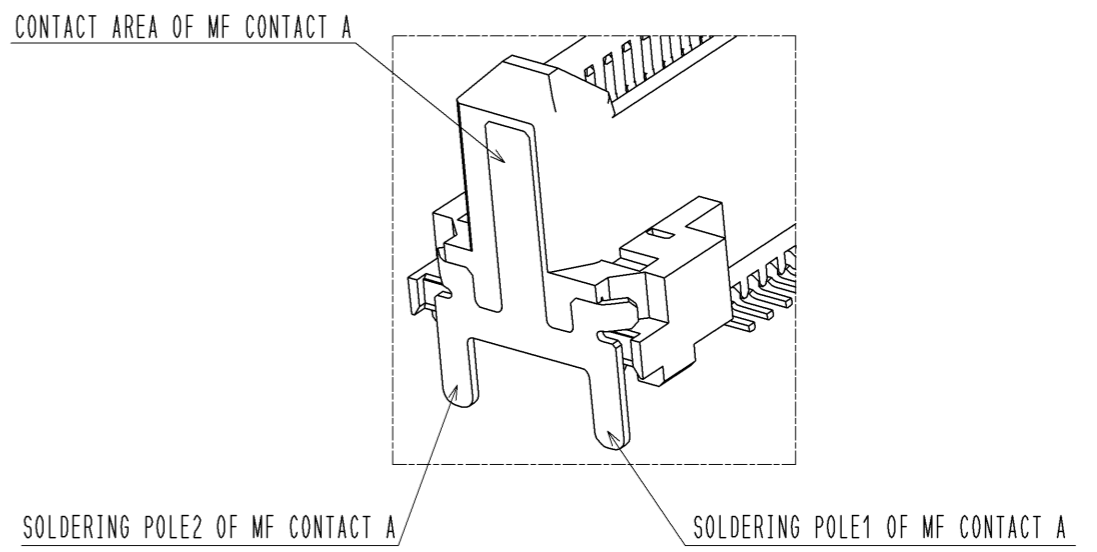


5 DRAWING FOR PACKING(1:2)

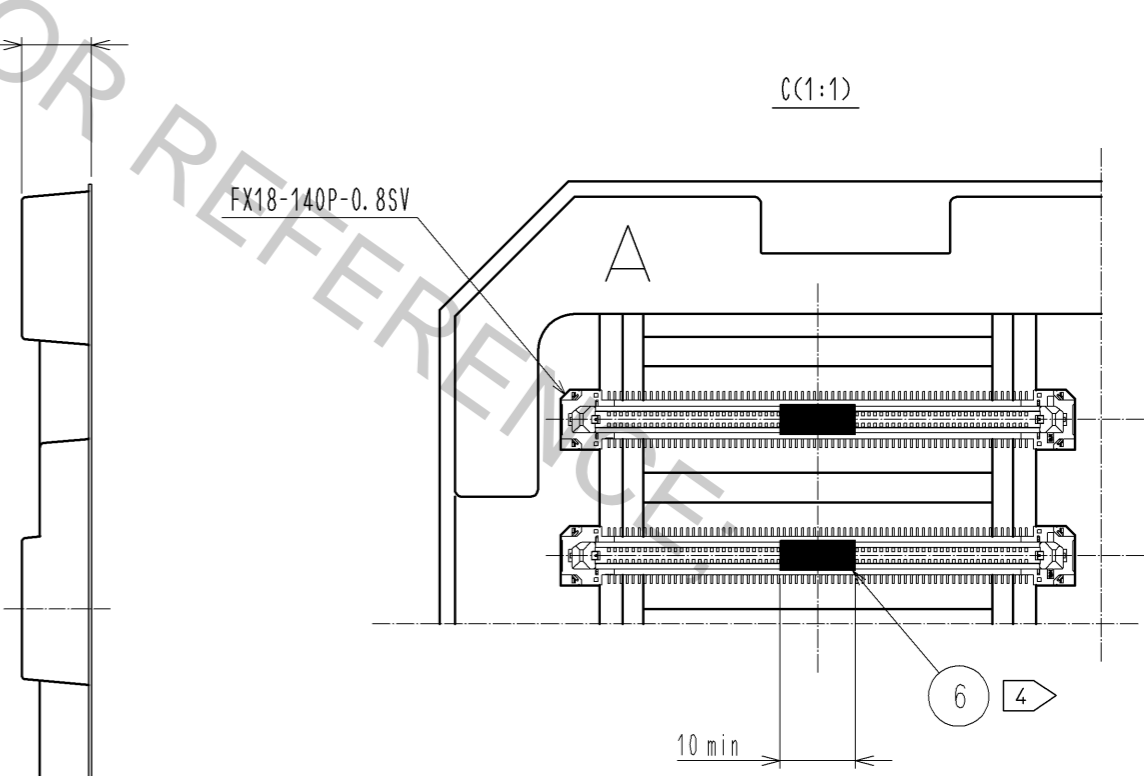


QTY. 40 >PS<

8 CONFIGURATION OF MF CONTACT A



NOTE 8 SOLDERING LEAD OF MF CONTACT A SPLITS INTO TWO POLES.
BE SURE TO CONNECT TO THE SAME CIRCUIT.



HRS	DRAWING NO.	EDC3-159565-00	△ 2/2
	PART NO.	FX18-140P-0.8SV	
	CODE NO.	CL579-0021-0-00	